

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Anthony L. Coyle, et al.

Serial No.:

09/992,387

Filed:

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For:

Flip-Chip On Film Assembly For Ball Grid Array

Packages

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Examiner:

Conf. No.:

Lewis, M.

Art Unit.:

INFORMATION DISCLOSURE STATEMENT

November 6, 2002

Assistant Commissioner For Patents

Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(A)

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.

Applicant wishes to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449. Copies of the listed references are enclosed.

If required, please charge the necessary fee of \$180 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

Michael K. Skrehot Attorney for Applicants

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